JOC355X

Rev.A.1.0

DESCRIPTION:

The products are Darlington transistor opto-couplers in a plastic SOP4 package. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector. With the robust coplanar double mold structure, the device provides the most stable isolation feature. The products are widely used in switch mode power supplies, programmable controllers, household appliances and office equipment.

MAIN FEATURES

High isolation 3750 VRMS
Operating temperature range -55°C to 110°C
RoHS & REACH Compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I		

Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

NOTE1100 s pulse, 100Hz frequency
NOTE2 AC for 1minute, R.H.=40~60%

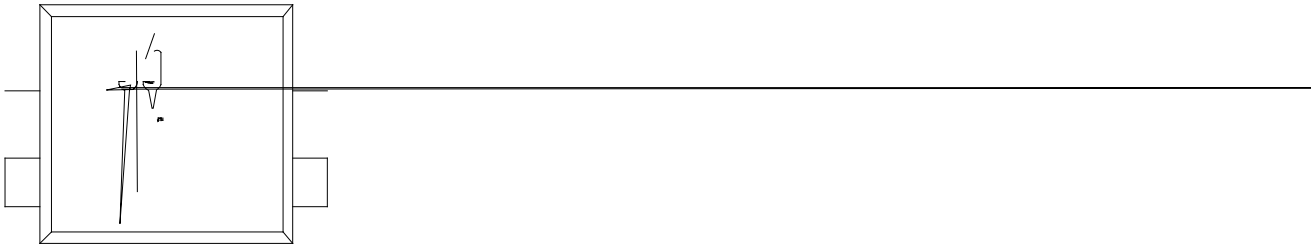
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	A
	Terminal Capacitance	C_t	V=0, f=1MHz	-	10	-	pF
Output	Collector-Emitter dark current	I_{CEO}	V_{CE}=20V, I_F=0	-	-	200	nA
	Collector-Emitter breakdown voltage	BV_{CEO}	I_C=0.1mA I_F=0	80	-	-	V
	Current transfer ratio	CTR	I_F=1mA V_{CE}=2V	1000	-	7500	%

Transfer
Characteristics

ORDERING AND MARKING INFORMATION

MARKING INFORMATION



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

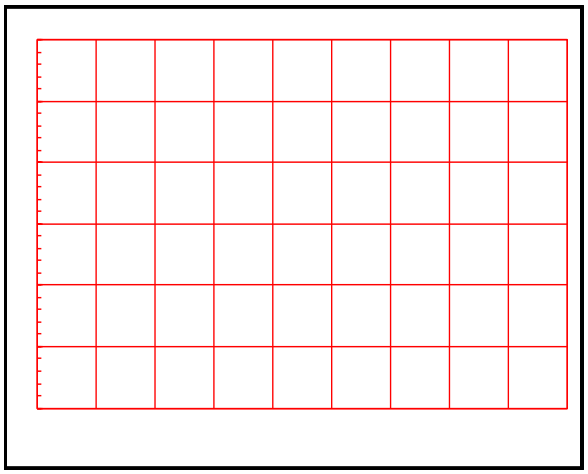
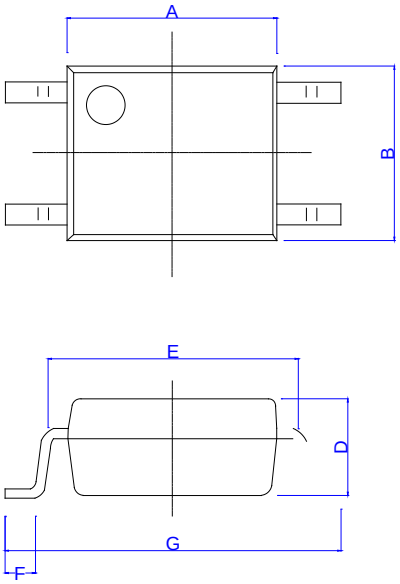


FIG.2: Collector Power Dissiption vs. Ambient Temperature

Package Dimension (Unit: mm)

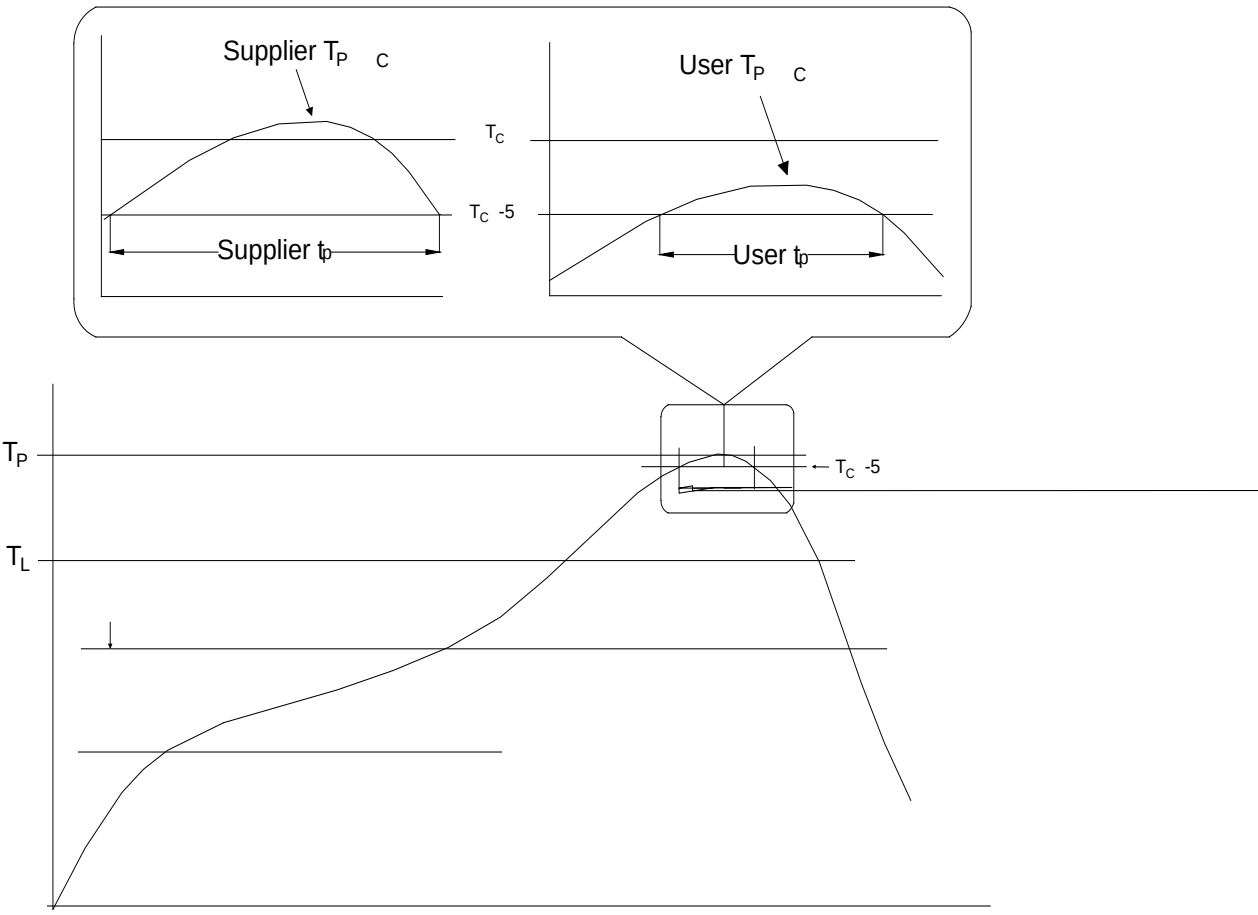


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C						
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F						
G	6.70			0.264		
H						
I						
J						

JOC355X

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REFLOW INFORMATION



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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